2SC5026

Silicon NPN epitaxial planar type

For low-frequency output amplification Complementary to 2SA1890

■ Features

- Low collector-emitter saturation voltage V_{CE(sat)}
- ullet High collector-emitter voltage (Base open) V_{CEO}
- Mini Power type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	80	V	
Collector-emitter voltage (Base open)	V _{CEO}	80	V	
Emitter-base voltage (Collector open)	V _{EBO}	5	V	
Collector current	Ic	1	A	
Peak collector current	I_{CP}	1.5	A	
Collector power dissipation *	P _C	1	W	
Junction temperature	T_{j}	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	

Note) *: Copper plate at the collector is more than 1 cm² in area, 1.7 mm in thickness Absolute maximum rating without heat sink for P_C is 0.5 W

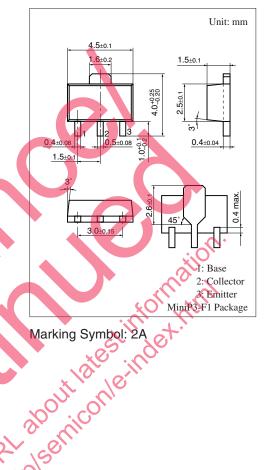
■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Electrical Orial acteristics T _a = 23 C±3 C						
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 10 \ \mu A$, $I_{\rm E} = 0$	80			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 1 \text{ mA}, I_B = 0$	80			V
Emitter-base voltage (Collector open)	V_{EBO}	$J_E = 10 \mu\text{A}, I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 40 \text{ V}, I_E = 0$			0.1	μΑ
Forward current transfer ratio	h _{FE1} *2	$V_{CE} = 2 \text{ V}, I_{C} = 100 \text{ mA}$	120		340	_
	h _{FE2} *1	$V_{CE} = 2 \text{ V}, I_{C} = 500 \text{ mA}$	60			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.15	0.3	V
Base-emitter saturation voltage *	V _{BE(sat)}	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.85	1.2	V
Transition frequency	f_T	$V_{CB} = 10 \text{ V}, I_{E} = -50 \text{ mA}, f = 200 \text{ MHz}$		120		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		10	20	pF
(Common base, input open circuited)						

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

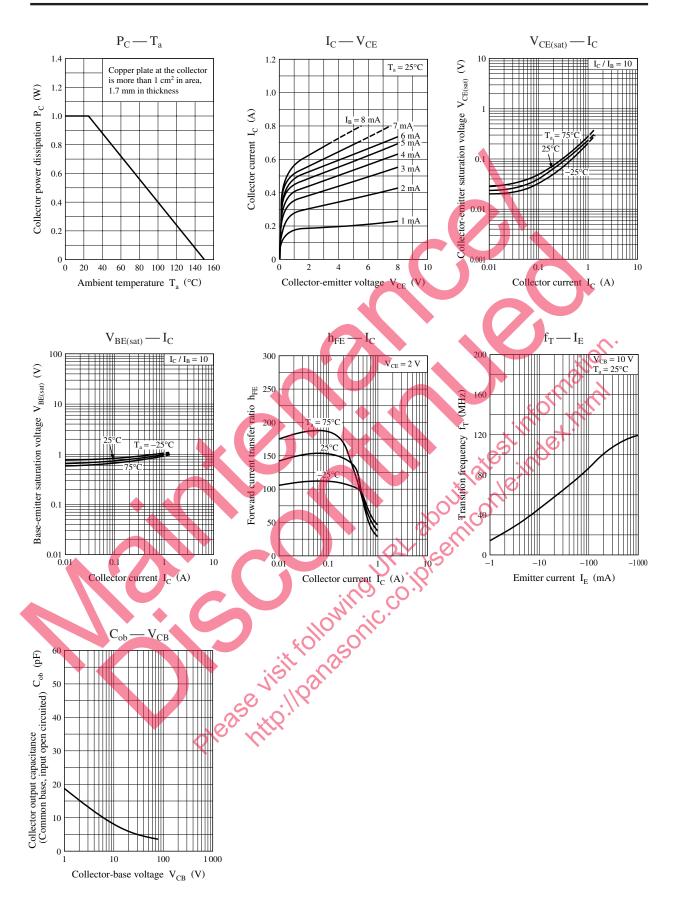
- 2. *1: Pulse measurement
 - *2: Rank classification

Rank	R	S
h _{FE1}	120 to 240	170 to 340



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